



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Appln. Of: MATSUDA
Serial No.: 09/222,524
Filed: December 28, 1998
For: SEMICONDUCTOR DEVICE
Group: 2811
Examiner: Parekh

DOCKET:
NEC N98039 CON

#9/C
4/30/01
RECEIVED
APR 26 2001
TECHNOLOGY CENTER 2800

The Assistant Commissioner of Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Dear Sir:

Prior to examination of the subject continuation application, please amend the application as follows:

IN THE CLAIMS:

Kindly cancel claims 1-20, without prejudice.

Please add new claims 21-44 reading as follows:

Sub D'
C1

--21. A semiconductor device comprising:
a wiring substrate having a predetermined pattern of wiring formed on one surface;
a semiconductor chip disposed on the other surface of said wiring substrate and having two or more chip electrodes in a common wiring layer, wherein said chip electrodes are arranged from an edge of said semiconductor chip toward its inner side;